

# BRC50N06DP

Rev.B Aug.-2023

## / Descriptions

TO-252            N  
N-CHANNEL MOSFET in a TO-252 Plastic Package.

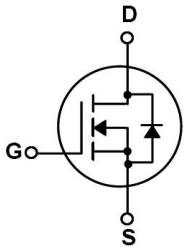
## / Features

Low  $R_{DS(on)}$ , low gate charge, low  $C_{rss}$ , fast switching, Trench Technologies, HF Product.

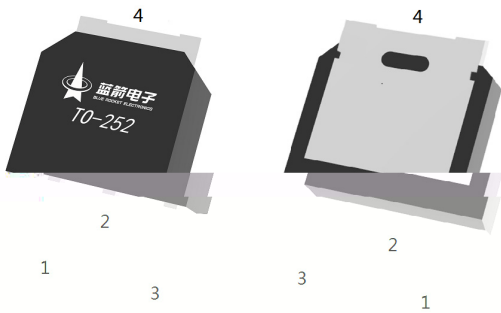
## / Applications

Suited for low voltage applications such as automotive, DC/DC Converters, and high efficiency switching for power management in portable and battery operated products.

## / Equivalent Circuit



## / Pinning



PIN1 G            PIN 2 D            PIN 3 S            PIN 4 D

## / Marking

See Marking Instructions.

## / Absolute Maximum Ratings(Ta=25 )

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Drain Current	$I_D(T_C=25)$	50	A
Drain Current - Pulsed	$I_{DM}$	200	A
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Avalanche Current	$I_{AS}$	20	A
Single Pulsed Avalanche Energy	$E_{AS}$	170	mJ
Power Dissipation	$P_D(T_C=25)$	60	W
Storage Temperature Range	$T_{stg}$	-55 150	
Thermal Resistance-Junction to Case	$R_{JC}$	2.1	/W
Thermal Resistance-Junction to Ambient	$R_{JA}$	50	

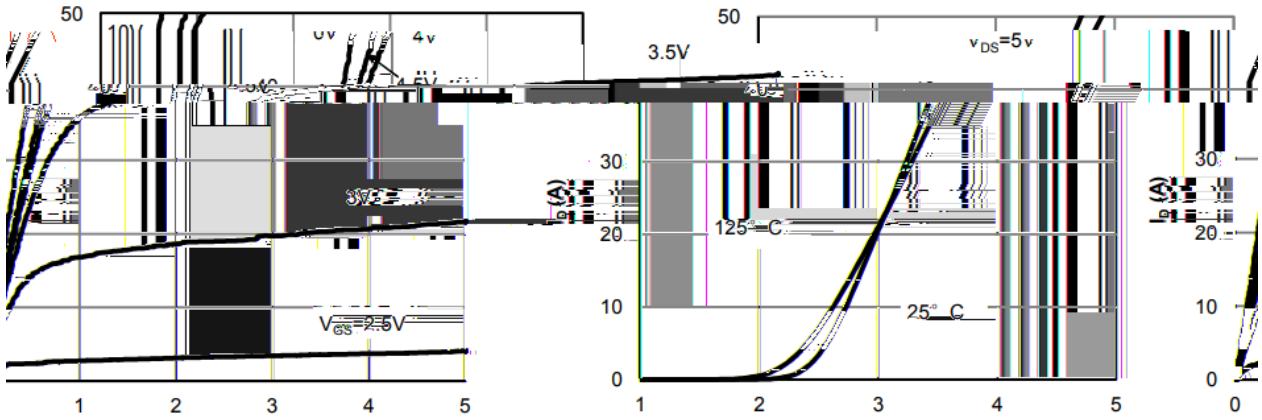
## / Electrical Characteristics(Ta=25 )

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$BV_{DS}$	$V_{GS}=0V$ $I_D=250\mu A$	60	66		V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=60V$ $V_{GS}=0V$			1.0	$\mu A$
		$V_{DS}=48V$ $T_C=150$			10	
Gate-Body Leakage Current Forward	$I_{GSS}$	$V_{GS}=\pm 20V$ $V_{DS}=0V$			$\pm 0.1$	$\mu A$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=250\mu A$	1	1.7	3	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V$ $I_D=25A$		11.8	15	m $\Omega$
		$V_{GS}=4.5V$ $I_D=18A$		15.5	20	
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V$ $I_S=1A$			1.25	V
Gate resistance	$R_g$	$V_{GS}=0V$ $V_{DS}=0V$ , $f=1MHz$		1.49		$\Omega$
Input Capacitance	$C_{iss}$	$V_{DS}=25V$ $V_{GS}=0V$ $f=1.0MHz$		1010		pF
Output Capacitance	$C_{oss}$			250		
Reverse Transfer Capacitance	$C_{rss}$			280		
Total Gate Charge	$Q_g(10V)$	$V_{GS}=10V$ $V_{DS}=30V$ $I_D=20A$		47.5	68	nC
Total Gate Charge	$Q_g(4.5V)$			24	35	
Gate Source Charge	$Q_{gs}$			6		
Gate Drain Charge	$Q_{gd}$			14.5		

**/ Electrical Characteristics(Ta=25 )**

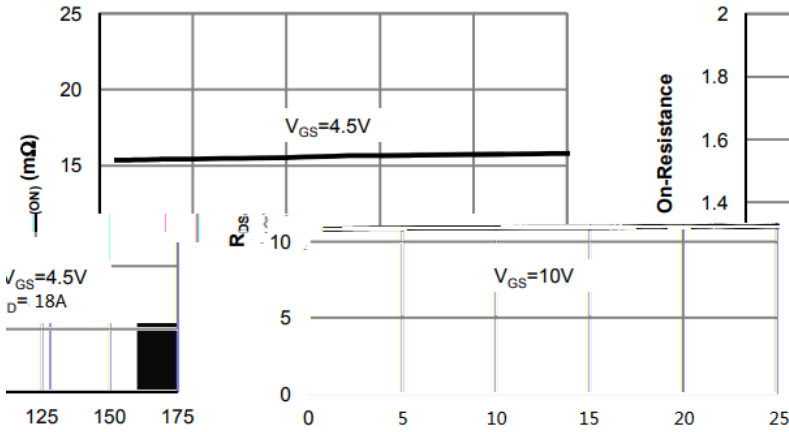
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=10V$ $V_{DS}=30V$ $R_L=1.5$ $R_{GEN}=3\Omega$		8		ns
Turn-On Rise Time	$t_r$			5		
Turn-Off Delay Time	$t_{d(off)}$			30		
Turn-Off Fall Time	$t_f$			5.5		

/ Electrical Characteristic Curve

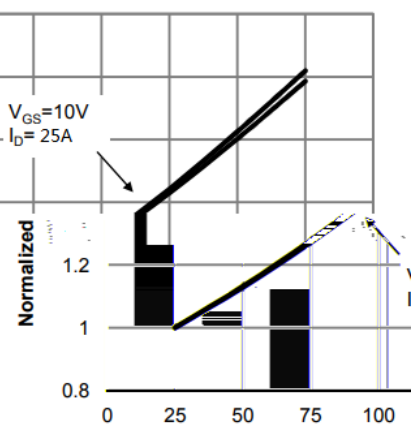


**Figure 1: On-Region Characteristics**

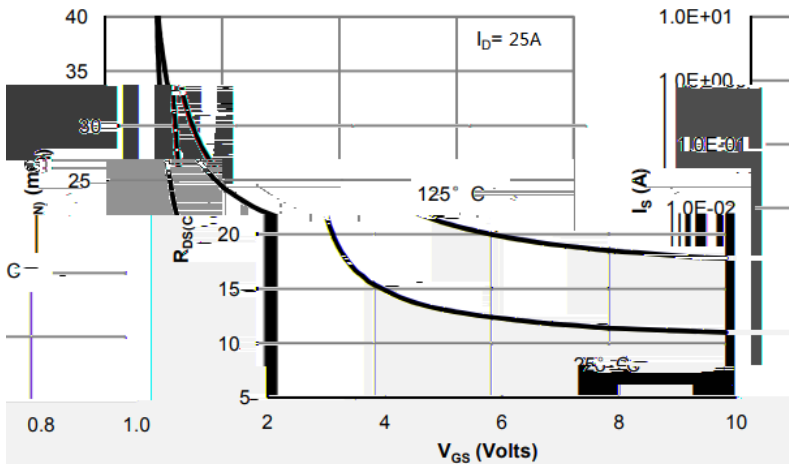
**Figure 2: Transfer Characteristics**



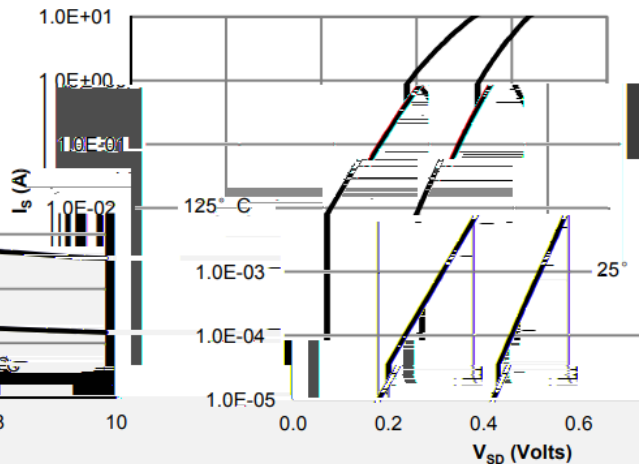
**Figure 3: On-Resistance vs. Drain Current and Gate Voltage**



**Figure 4: On-Resistance vs. Temperature**



**Figure 5: On-Resistance vs. Gate-Source Voltage**



**Figure 6: Body-Diode Characteristics**

/ Electrical Characteristic Curve

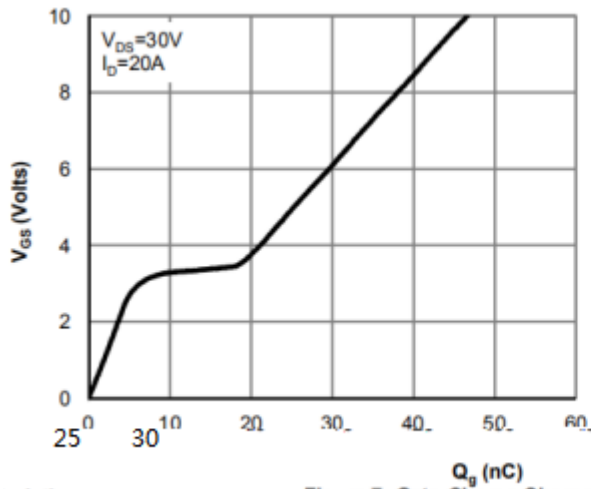


Figure 7: Gate-Charge Characteristics

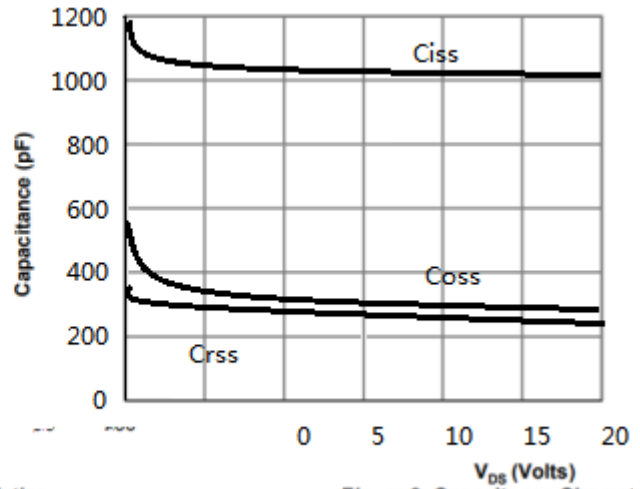


Figure 8: Capacitance Characteristics

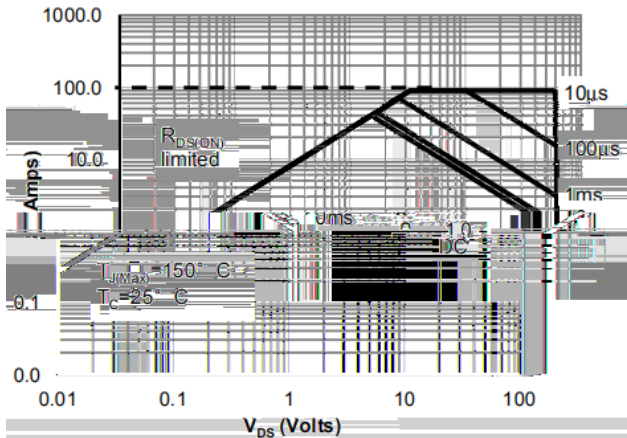


Figure 9: Maximum Forward Biased Safe Operating Area

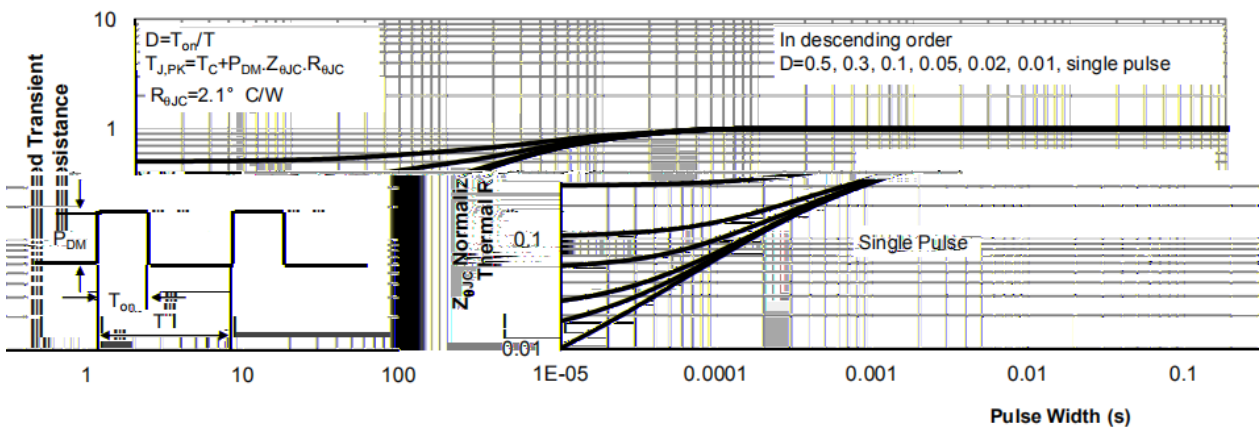
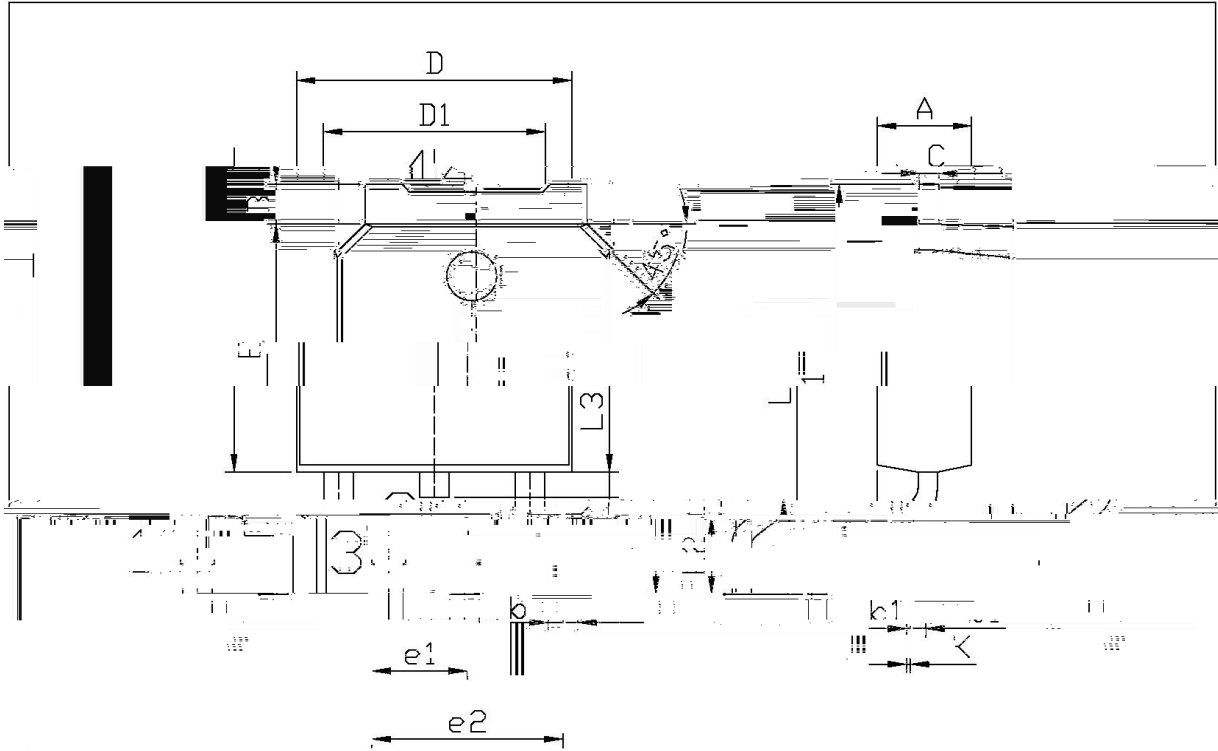


Figure 10: Normalized Maximum Transient Thermal Impedance

**/ Package Dimensions**

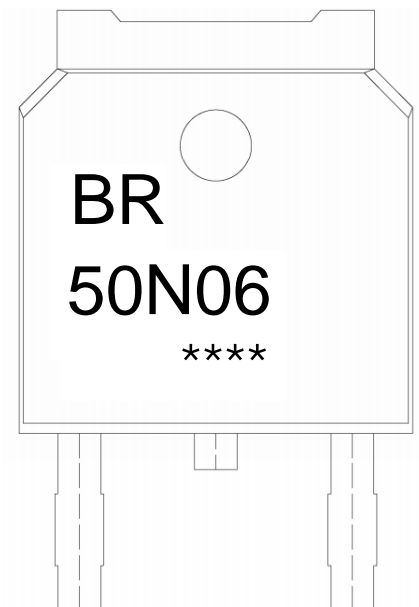


单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	6.25	6.25	A	2.40	2.40
B	2.34	2.34	B	1.25	1.25
C	4.73	4.73	C	0.99	0.99
D	10.35	10.35	D	0.55	0.55
E	0.45	0.55	E	1.70	2.00
L3	0.45	0.55	L3	0.60	0.60
e1	0.45	0.55	e1	0.00	0.00
e2	0.45	0.55	e2	0.00	0.00
b	0.45	0.55	b	0.00	0.00
k	0.45	0.55	k	0.00	0.00
k1	0.45	0.55	k1	0.00	0.00

TO-252

**/ Marking Instructions**



BR

50N06

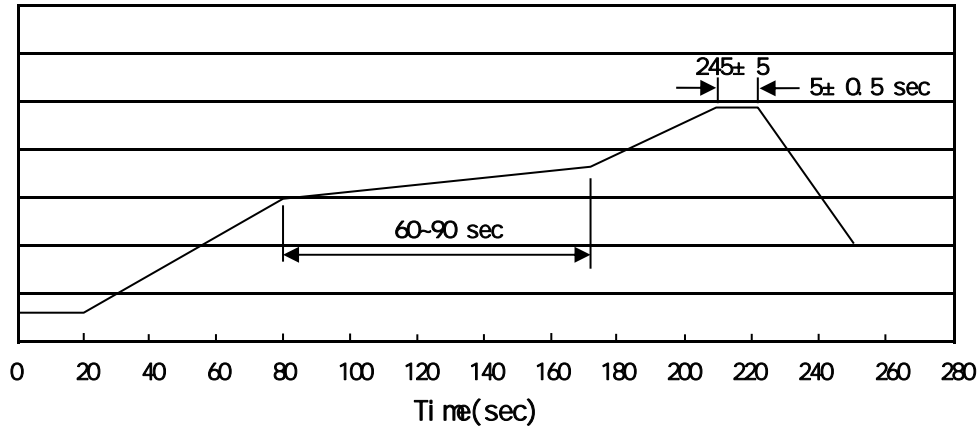
Note:

BR: Company Code

50N06: Product Type Code

\*\*\*\*: Lot No. Code, code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |     |     |    |          |   |
|---|-----|-----|----|----------|---|
| 1 | 150 | 180 | 60 | 90sec;   | 1.Preheating:150~180 , Time:60~90sec.   |
| 2 | 245 | 5   | 5  | 0.5sec;  | 2.Peak Temp.:245 5 , Duration:5 0.5sec. |
| 3 |     |     | 2  | 10 /sec. | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

260 5                      10 1 sec.                      Temp.:260±5                      Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
TO-252	2,500	2	5,000	6	30,000	13 x16	360x360x50	380x335x366

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-251/252	75	48	3,600	5	18,000	526x20.5x5.25	555x164x50	575x290x180

/ Notices